

Examiner's Copy

AN 1996:466778 HCAPLUS
DN 125:148796
TI Dilute **tin** alloys for lead-free **solders**
IN Matsumoto, Toshio; Muraoka, Naoki; Masuda, Toshuki; Omoto, Takahiko;
Ozaki, Jinichi
PA Ishikawa Kinzoku Kk, Japan
SO Jpn. Kokai Tokkyo Koho, 3 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 08132277	A2	19960528	JP 1994-269023	19941101
PRAI	JP 1994-269023		19941101		
AB	The Pb-free solders are Sn alloys contg. Ag 1.0-3.0, Cu 0.5-2.0, and Bi 1.0-10.0%.				